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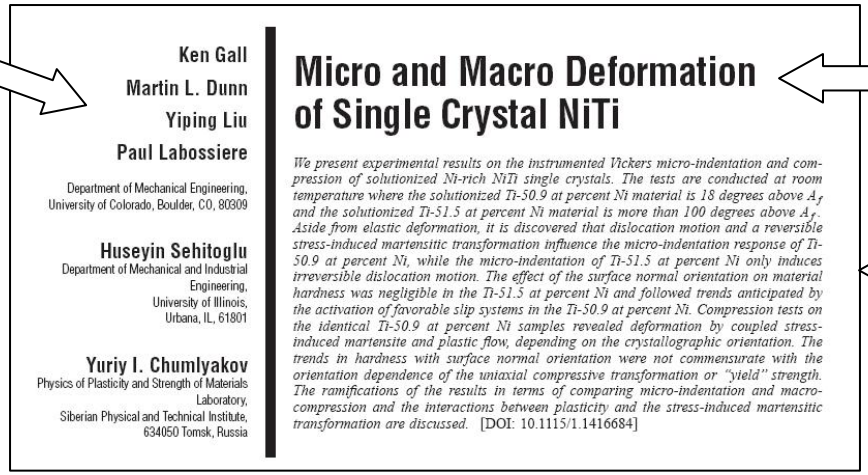

Ken Gall
Martin L. Dunn
Yiping Liu
Paul Labossiere

Department of Mechanical Engineering, University of Colorado, Boulder, CO, 80309

Huseyin Sehitoglu
Department of Mechanical and Industrial Engineering, University of Illinois, Urbana, IL, 61801

Yuriy I. Chumlyakov
Physics of Plasticity and Strength of Materials Laboratory, Siberian Physical and Technical Institute, 634050 Tomsk, Russia

Micro and Macro Deformation of Single Crystal NiTi

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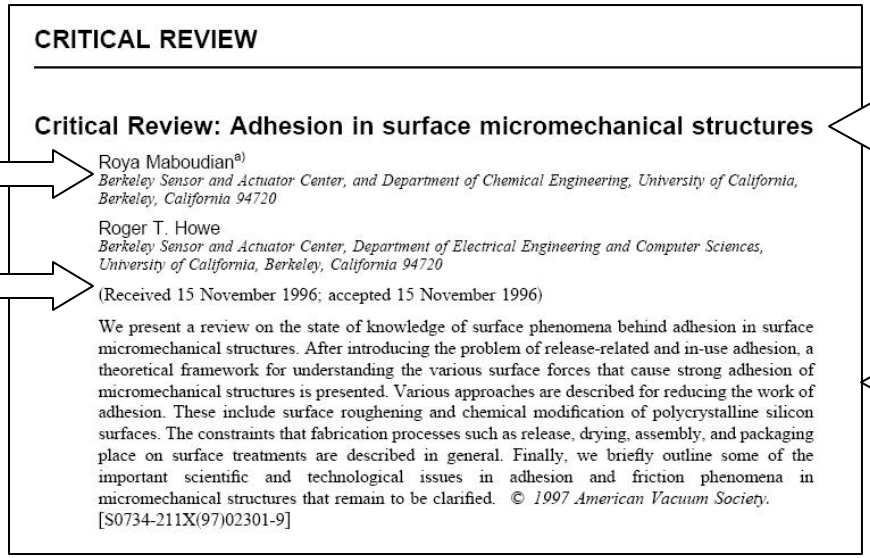

CRITICAL REVIEW

Critical Review: Adhesion in surface micromechanical structures

Roya Maboudian[a)]
Berkeley Sensor and Actuator Center, and Department of Chemical Engineering, University of California, Berkeley, California 94720

Roger T. Howe
Berkeley Sensor and Actuator Center, Department of Electrical Engineering and Computer Sciences, University of California, Berkeley, California 94720

(Received 15 November 1996; accepted 15 November 1996)

We present a review on the state of knowledge of surface phenomena behind adhesion in surface micromechanical structures. After introducing the problem of release-related and in-use adhesion, a theoretical framework for understanding the various surface forces that cause strong adhesion of micromechanical structures is presented. Various approaches are described for reducing the work of adhesion. These include surface roughening and chemical modification of polycrystalline silicon surfaces. The constraints that fabrication processes such as release, drying, assembly, and packaging place on surface treatments are described in general. Finally, we briefly outline some of the important scientific and technological issues in adhesion and friction phenomena in micromechanical structures that remain to be clarified. © *1997 American Vacuum Society.*
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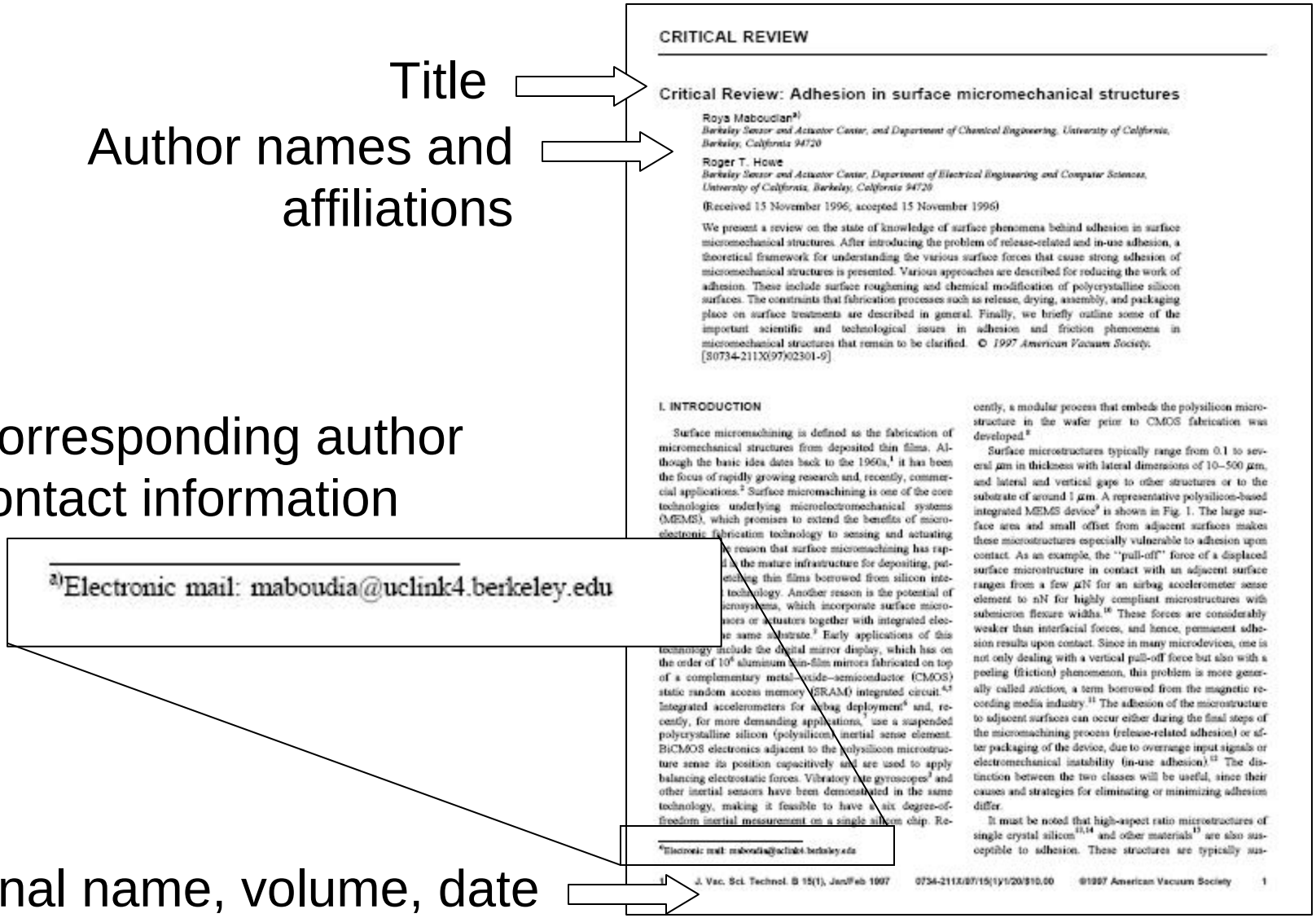

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I. INTRODUCTION

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Surface microstructures typically range from 0.1 to several μm in thickness with lateral dimensions of 10–500 μm, and lateral and vertical gaps to other structures or to the substrate of around 1 μm. A representative polysilicon-based integrated MEMS device[9] is shown in Fig. 1. The large surface area and small offset from adjacent surfaces makes these microstructures especially vulnerable to adhesion upon contact. As an example, the "pull-off" force of a displaced surface microstructure in contact with an adjacent surface ranges from a few μN for an airbag accelerometer sense element to nN for highly compliant microstructures with submicron flexure widths.[10] These forces are considerably weaker than interfacial forces, and hence, permanent adhesion results upon contact. Since in many microdevices, one is not only dealing with a vertical pull-off force but also with a peeling (friction) phenomenon, this problem is more generally called *stiction*, a term borrowed from the magnetic recording media industry.[11] The adhesion of the microstructure to adjacent surfaces can occur either during the final steps of the micromachining process (release-related adhesion) or after packaging of the device, due to overrange input signals or electromechanical instability (in-use adhesion).[12] The distinction between the two classes will be useful, since their causes and strategies for eliminating or minimizing adhesion differ.

It must be noted that high-aspect ratio microstructures of single crystal silicon[13,14] and other materials[15] are also susceptible to adhesion. These structures are typically sus-

[a)]Electronic mail: maboudia@uclink4.berkeley.edu

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Ken Gall
Martin L. Dunn
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Paul Labossiere

Department of Mechanical Engineering,
University of Colorado, Boulder, CO, 80309

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1 Introduction

Traditional applications of NiTi shape memory alloys include clamps, pipe couplings, actuators, orthodontic wires, blood clot filters, stents, and orthopedic devices [1]. The aforementioned applications exploit the ability of NiTi shape memory alloys to recover inelastic strains on the order of 6 percent by heating (shape memory) or stress removal (pseudoelasticity). We currently understand that a thermo-elastic martensitic transformation from a B2 phase to a monoclinic phase controls the unique thermo-mechanical properties of near equiatomic NiTi when it is deformed near its transformation temperatures [2,3]. Moreover, based on a recent review [4], it is clear that we have a rather solid comprehension of the fundamental macroscopic and microscopic deformation modes resulting from the transformation in NiTi shape memory alloys deformed under monotonic loading. Aside from our breadth of knowledge for NiTi deformed under monotonic loading, we do not have a strong grasp of microscopic deformation mechanisms under cyclic loading. It is surprising that such a deficiency in knowledge exists, despite the fact that NiTi [5–23].

Previous experimental work has provided data on the *macroscopic* response of polycrystalline NiTi to pure mechanical [6–11,15] pure thermal [12–15], or thermo-mechanical [15–23] cyclic loading. The aforementioned collection of work provides information on the effects of cycle number, loading path, stress state, stress level, strain level, temperature, and material heat treatment. A common conclusion in all cyclic studies is that the material response generally changes during cycling and the evolution is somehow linked to the interaction between transformation strains and strains due to plastic flow. Only very recent studies have attempted to explicitly uncover the *microscopic* mechanisms for cyclic evolution and degradation effects in NiTi using single crystals [24] and transmission electron microscopy (TEM) [25]. Understanding the microscopic mechanisms of cyclic degradation in NiTi materials is particularly important for emerging shape memory alloys technologies.

Ongoing workshops [26] and conferences [27] have suggested that a lucrative future for shape memory materials such as NiTi lies in the areas of micro-electro-mechanical systems (MEMS) and civil infrastructures. Long-life reliability issues in these applications demand tools to understand and accurately predict the evolution of the NiTi material response under cyclic loading. To improve our state-of-the-art approaches [20–23] aimed at modeling the cyclic behavior of NiTi shape memory alloys, we must increase our mechanistic understandings at the microscopic scale.

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explicitly focused on the mechanisms and implications of plastic flow. Ignoring the effects of plastic flow is a viable assumption under monotonic loading since its influence is negligible over one loading cycle. However, under cyclic loading, the local plastic flow characteristics of the B2 matrix have a strong influence on the evolving NiTi material response [24]. During the transformation, the material microstructure is a mixture of martensite, the B2 parent phase, and untransformable precipitates (present in Ni or Ti rich materials). Repeated growth of the martensite through a heterogeneous microstructure causes local slip to accumulate to significant levels in the weaker B2 phase. To our knowledge, there is only one study that examines microscopic slip characteristics in NiTi materials [32], where TEM is used to identify the (100){001} and (100){011} families as dominant slip systems in B2 NiTi. Notably, experimental [33] and atomistic [34] studies in similar B2 NiAl intermetallics have provided consistent findings with the above slip systems for B2 NiTi.

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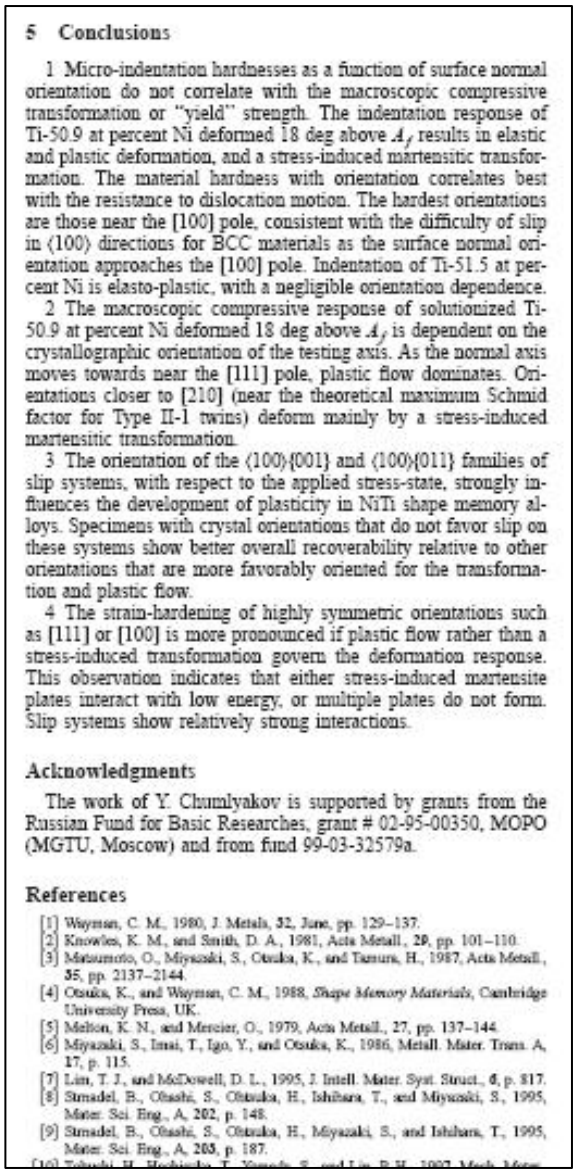

5 Conclusions

1 Micro-indentation hardnesses as a function of surface normal orientation do not correlate with the macroscopic compressive transformation or "yield" strength. The indentation response of Ti-50.9 at percent Ni deformed 18 deg above A_f results in elastic and plastic deformation, and a stress-induced martensitic transformation. The material hardness with orientation correlates best with the resistance to dislocation motion. The hardest orientations are those near the [100] pole, consistent with the difficulty of slip in ⟨100⟩ directions for BCC materials as the surface normal orientation approaches the [100] pole. Indentation of Ti-51.5 at percent Ni is elasto-plastic, with a negligible orientation dependence.

2 The macroscopic compressive response of solutionized Ti-50.9 at percent Ni deformed 18 deg above A_f is dependent on the crystallographic orientation of the testing axis. As the normal axis moves towards near the [111] pole, plastic flow dominates. Orientations closer to [210] (near the theoretical maximum Schmid factor for Type II-1 twins) deform mainly by a stress-induced martensitic transformation.

3 The orientation of the ⟨100⟩{001} and ⟨100⟩{011} families of slip systems, with respect to the applied stress-state, strongly influences the development of plasticity in NiTi shape memory alloys. Specimens with crystal orientations that do not favor slip on these systems show better overall recoverability relative to other orientations that are more favorably oriented for the transformation and plastic flow.

4 The strain-hardening of highly symmetric orientations such as [111] or [100] is more pronounced if plastic flow rather than a stress-induced transformation govern the deformation response. This observation indicates that either stress-induced martensite plates interact with low energy, or multiple plates do not form. Slip systems show relatively strong interactions.

Acknowledgments

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Conclusions

Acknowledgements and funding source(s)

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ACKNOWLEDGMENTS

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Ken Gall
Martin L. Dunn
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Department of Mechanical Engineering, University of Colorado, Boulder, CO, 80309

Huseyin Sehitoglu
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One of the primary reasons that the micro-mechanisms of cyclic evolution and degradation effects have eluded research efforts is because fundamental research on the NiTi alloy system has not explicitly focused on the mechanisms and implications of plastic flow. Ignoring the effects of plastic flow is a viable assumption under monotonic loading since its influence is negligible over one loading cycle. However, under cyclic loading, the local plastic flow characteristics of the B2 matrix have a strong influence on the evolving NiTi material response [24]. During the transformation, the material microstructure is a mixture of martensite, the B2 parent phase, and untransformable precipitates (present in Ni or Ti rich materials). Repeated growth of the martensite through a heterogeneous microstructure causes local slip to accumulate to significant levels in the weaker B2 phase. To our knowledge, there is only one study that examines microscopic slip characteristics in NiTi materials [32], where TEM is used to identify the {100}⟨001⟩ and {100}⟨011⟩ families as dominant slip systems in B2 NiTi. Notably, experimental [33] and atomistic [34] studies in similar B2 NiAl intermetallics have provided consistent findings with the above slip systems for B2 NiTi.

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a)Electronic mail: maboudia@aclight.berkeley.edu

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  - Look at all the figures before reading the text
  - Focus on a particular aspect (like the experimental techniques for instance)
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